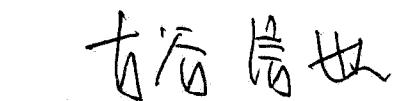


**VERIFICATION OF TRANSLATION**

I, the undersigned Shinya Furutani, Japanese Patent Attorney, having an office at  
1-27, Dojima 2-chome, Kita-ku, Osaka 530-0003 JAPAN,  
declare that I am well acquainted with the Japanese and English languages, and that the attached  
English text is, to the best of my knowledge, a complete and accurate translation from the Japanese  
text of page 2, line 18 to page 3, line 7; page 4, lines 14 to 26; page 10 line 26 to page 11, line 6;  
claims 2 and 4 of the specification of PCT Application No. PCT/JP03/04469, which corresponds to  
page 3, line 14 to page 4, line 13; page 6, line 11 to page 7, line 4; page 14, line 21 to page 15, line 5;  
original claims 2 and 4 (before preliminary amendment) of the U.S. Patent Application Serial  
No.:10/510,905.

The undersigned further declares that all statements made herein of his/her own knowledge are  
true, and all statements made on information and belief are believed to be true, and that these  
statements were made with the knowledge that willful false statements and the like, so made, are  
punishable by fine and/or imprisonment under Section 1001 of Title 18 of the United States Code, and  
that any such willful false statements may jeopardize the validity of the application or any patent  
resulting therefrom.

Date: 12/13/2007



Signature of verifying person

Shinya Furutani

Printed Name of verifying person

Accurate English Translation of the description at page 2, line 18 to page 3, line 7 of PCT Application No. PCT/JP03/04469, which should have appeared at page 3, line 14 to page 4, line 13 of the present specification

In other words, the present invention provides a material for slush molding comprising a thermoplastic polyurethane resin (A) (hereinafter, may also be called a resin (A)) in which the difference (hereinafter, abbreviated as DST) between the softening starting temperature and the softening ending temperature (hereinafter, abbreviated as STi and STe, respectively) by the thermomechanical analysis penetration mode of the resin (A) is from 0 to 30°C and in which STi is 135 to 200°C. The resin (A) preferably comprises a polyurethane resin having a hard segment (A1) with a number average molecular weight of 200 to 2000 comprising a diisocyanate (a1) having a symmetrical structure, and at least one species selected from the group consisting of a low molecular-weight diamine (a2) having a symmetrical structure and a low molecular-weight diol (a3), and a soft segment (A2) comprising a high molecular-weight diol (a4) with a number average molecular weight of 500 to 5000, with the content of hard segment in the resin being from 5 to 50% by weight, the content of aromatic rings in the resin being 35% by weight or less, and the content of aromatic rings and the content of urea groups satisfying the following equation (i):

$$-0.1x + 2.5 \leq y \leq -0.1x + 6 \quad (i)$$

wherein x represents the content (% by weight) of aromatic rings in the resin (A), and y the content (% by weight) of urea groups in the resin (A).

Accurate English Translation of the description at page 4, lines 14 to 26 of PCT

Application No. PCT/JP03/04469, which should have appeared at page 6, line 11 to  
page 7, line 3 of the present specification

A thermoplastic polyurethane resin (A) in the present invention preferably comprises, for example, a polyurethane resin having a hard segment (A1) with a number average molecular weight (hereinafter, Mn) of 200 to 2000 comprising a diisocyanate (a1) having a symmetrical structure, and at least one species selected from the group consisting of a low molecular-weight diamine (a2) having a symmetrical structure and a low molecular-weight diol (a3), and a soft segment (A2) comprising a high molecular-weight diol (a4) with an Mn of 500 to 5000, with the content of hard segment in the polyurethane resin being from 5 to 50% by weight, the content of aromatic rings in the polyurethane resin being 35% by weight or less, and the content of aromatic rings and the content of urea groups satisfying the following relation (i):

$$-0.1x + 2.5 \leq y \leq -0.1x + 6 \quad (i)$$

wherein x represents the content (% by weight) of aromatic rings in the polyurethane resin, and y the content (% by weight) of urea groups in the polyurethane resin.

Accurate English Translation of the description at page 10 line 26 to page 11, line 6 of PCT Application No. PCT/JP03/04469, which should have appeared at page 14, line 21 to page 15, line 5 of the present specification

In the present invention, the Mn of a hard segment (A1) made up of the above-described diisocyanates (a1), and at least one species selected from the group consisting of the above-described diamines (a2) and the above-described low molecular-weight diols (a3) is preferably from 200 to 2000, more preferably from 300 to 1000. From the viewpoint of a sharp melt properties, the Mn is preferably 200 or more, and from the standpoint of STi, the Mn is preferably 2000 or less. The Mn of the hard segment (A1) can be calculated from the following equation (ii).

Accurate English Translation of the claim 2 of PCT Application No. PCT/JP03/04469,  
which should have appeared as original claim 2 (before preliminaly amendment) at  
pages 58 - 59 of the present specification:

2. The material for molding according to claim 1, in which said resin (A) comprises a polyurethane resin having a hard segment (A1) with a number average molecular weight of 200 to 2000 comprising a diisocyanate (a1) having a symmetrical structure, and at least one species selected from the group consisting of a low molecular-weight diamine (a2) having a symmetrical structure and a low molecular-weight diol (a3); and a soft segment (A2) having a high molecular-weight diol (a4) with a number average molecular weight of 500 to 5000,  
with the content of hard segment in the resin (A) being from 5 to 50% by weight, the content of aromatic rings in the resin (A) being 35% by weight or less, and the content of aromatic rings and the content of urea groups satisfying the following relation (i):

$$-0.1x + 2.5 \leq y \leq -0.1x + 6 \quad (i)$$

wherein x represents the content (% by weight) of aromatic rings in the resin (A), and y the content (% by weight) of urea groups in the resin (A).

Accurate English Translation of the claim 4 of PCT Application No. PCT/JP03/04469,  
which should have appeared as original claim 4 (before preliminary amendment) at  
page 59 of the present specification:

4. The material for molding according to claim 2 or 3, in which  
said hard segment (A1) is a hard segment having a number average molecular weight of 200 to 2000 and comprising a diisocyanate (a1) having a symmetrical structure, and at least one species selected from the group consisting of a low molecular-weight diamine (a2) having a symmetrical structure and a low molecular-weight diol (a3') having a symmetrical structure.